

Notice of References Cited	Application/Contr. No. 09/763,891		Applicant(s)/Patent Under Reexamination UCHIDA ET AL.	
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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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*	B	US-4968381	11-1990	Prigge et al.	156/636
*	C	US-5434107	07-1995	Paranjpe	437/225
*	D	US-5691219	11-1997	Kawakubo et al.	437/52
*	E	US-5770095	06-1998	Sasaki et al.	216/38
*	F	US-5770103	06-1998	Wang et al.	252/79.1
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*	H	US-5932486	08-1999	Cook et al.	438/692
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	K	US-6206756-B1	03-2001	Chopra et al.	451/28
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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Hayashi, Y. et al., "A New Abrasive-Free, Chemical -Mechanical-Polishing for Aluminium Metallization of ULSI Devices, International Electron Devices Meeting Technical Digest, 1992, pp. 976-978.
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
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